

Certificate TW01/00039

The management system of

# Kinsus Interconnect Technology Corp.

No. 1245 & 1245-1, Zhonghua Rd., Xinwu Dist., Taoyuan City 327, Taiwan, R.O.C.

has been assessed and certified as meeting the requirements of

**ISO 14001:2015**

For the following activities

The manufacture and sale of printed circuit board, BGA substrate, flexible printed circuit board, flexible substrate for chip packaging and ABF carrier board.

This certificate is valid from 19 November 2024 until 19 November 2027 and remains valid subject to satisfactory surveillance audits.

Issue 13. Certified since 11 December 2001

Certified activities performed by additional sites are listed on subsequent pages.

*L. Moran*

Authorised by

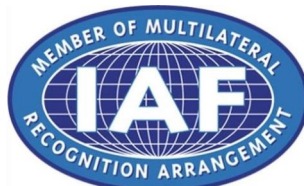
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Certificate TW01/00039, continued

# Kinsus Interconnect Technology Corp.



## ISO 14001:2015

Issue 13

### Sites

Kinsus Interconnect Technology Corp.

No. 1245 & 1245-1, Zhonghua Rd., Xinwu Dist., Taoyuan City 327, Taiwan, R.O.C.

The manufacture and sale of printed circuit board, BGA substrate, flexible printed circuit board, flexible substrate for chip packaging and ABF carrier board.

Kinsus Interconnect Technology Corp. & Second Plant

No. 1245 & 1245-1, Zhonghua Rd., Xinwu Dist., Taoyuan City 327, Taiwan, R.O.C.

The manufacture and sale of printed circuit board, BGA substrate, flexible printed circuit board, and flexible substrate for chip packaging.

Kinsus Interconnect Technology Corp. Tsing-Hua First Plant & Third Plant

No.810 & 810-1, Zhonghua Rd., Xinwu Dist., Taoyuan City 327, Taiwan, R.O.C.

The manufacture of printed circuit board, BGA substrate, flexible printed circuit board, and flexible substrate for chip packaging.

Kinsus Interconnect Technology Corp. Xing-Feng First Plant

No. 526 Sec. 2, Jianxing Rd., Xinfeng Township Hsinchu County 304, Taiwan, R.O.C.

The manufacture of printed circuit board, BGA substrate, flexible printed circuit board, and flexible substrate for chip packaging.

Kinsus Interconnect Technology Corp. Xing-Feng Second Plant

No. 12, Ln. 468, Sec. 2, Jianxing Rd., Xinfeng Township, Hsinchu County 304, Taiwan, R.O.C.

The manufacture of printed circuit board, BGA substrate, flexible printed circuit board, and flexible substrate for chip packaging.

Kinsus Interconnect Technology Corp. You-Shi Plant

No. 566-1, 580, Gaoshi Rd., Yangmei Dist., Taoyuan City 326, Taiwan, R.O.C.

The manufacture of ABF carrier board.



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